

Technical Data Sheet

F 169 SA35-86D30

No Clean Solder-Paste for Dispensing



1. Description

F169SA35-86D30 is a ready-to-use homogeneous mixtures low odour characteristics, consisting of metal powder, binders, solvents, fluxes and thixotropic agents.

Although this paste is optimised for dispensing application, it has a very low slump. Due to very small powder particles it can be dispensed through small needles without danger of clogging.

F169SA35-86D30 provides a good wettability and leaves clear flux residues.

It does not contain any halogen activators. The flux of F169SA35-86D30 has passed all tests for no clean solder pastes according to Siemens-standard SN 59650 (issue July 1994).

Due to its limited tack time this solder paste is suitable only for in-line production.

Key Benefits

- Excellent dispensability
- Stable viscosity
- Very low slump

2. Product indication

Indication: F169SA35-86D30

Alloy: Sn96,5/Ag3,5

3. Physical properties:

Metal powder:

Particle size: Type 3 = 25 –45 µm (325/+500 mesh)

Shape: Spherical

Melting Point: Sn96,5/Ag3,5 =221°C

Composition: Sn96,5/Ag3,5 = F169SA35-86D30

Density: Sn96,5/Ag3,5 = 7,4 g/cc

Solder Paste:

Metal Content: 86%

Viscosity Range: Physica CSR D=10 s⁻¹ : 35-80 Pas

Density: N/a

4. Reflow Parameters (recommendation)

- Reflow should be done under an inert atmosphere.
- For soldering under air we recommend a linear reflow profile.

5. Residue properties

| | | |
|-----------------------|------------------------------|-----------|
| Flux Activity: | According to ANSI- J-STD-004 | Klasse L0 |
| | DIN EN 29454-1 | 1.1.3.C |

6. Recommended Processing Guidelines

- Ensure that the paste has reached room temperature before opening, to prevent condensation.
- The flux residues don't need to be cleaned. They may remain on the circuit.
- For dispensing: depending on the nozzle-shape down to 0,3-0,4 mm. Cone-shaped nozzle is preferred.
- Clean wet paste with diverse Zestron and Vigon cleaning materials.
- The peak temperature depends on the heat capacity of the components.

7. Storage

- Store the solder paste in tightly-sealed syringes and avoid exposure to sunlight and high humidity.
- Min. 3 month in a refrigerator at 2-10°C
- Store syringes vertical, with tip down.

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